

PSMA Semiconductor Committee Meeting

Date: May 4th, 2016

Attendees: Ed, Ranbir, Joe Engle, Tim M., Aung, Ritu

Discussion:

1. APEC Update:

- The Industry session went very well and it was very well attended.
- The presentations were very good, in particular the one from Navitas
- The market research paper was a great complement, quite different from Yole's presentation last year. It covered more generic trends of the semiconductor industry
- The packaging presentation was not very well received.
- Overall, very interactive.
- For next year's Industry Session, we should still plan on having a paper on packaging, but focus more on L, C, R reduction, layout optimization, 3D packaging, etc. And look for a better advocate of all these developments.
- We also need to have more representation for SiC, at least two papers on that.
- We should continue to have a paper on Silicon
- Another suggestion was to have two Industry Sessions - one focused on components and one on applications?
- Here is a tentative list of topics that the team came up with:
 - a) Market research
 - b) Silicon Carbide - 2
 - c) GaN - 2 or 3
 - d) Packaging
 - e) Silicon

2. WiPDA Discussion

- Nothing has started yet between WiPDA and PSMA. Aung said he'll check on the status of the MoU, if there is one in place.
- Need to decide what all we can commit to? Primarily the support for exhibits. We should consider increasing the price for the booths.
- We should also plan to have more number of booths this time.

3. Other topics

- Tim McDonald informed the team that they have formed a group with a mission to formulate standards for testing, reliability, datasheets, qualification, etc. for wide band gap devices. Companies like JEDEC, EPC, Navitas are already involved in these discussions. Tim will keep us all updated on the progress this team makes.
- Tim also mentioned that he has been approached by Conor Q. to participate in the PSMA roadmap development. He will keep us all informed of what progress is made there and also how the rest of us can be involved in those discussions and provide our inputs.

Actions:

1. Check if there is any MoU already signed between WiPDA and PSMA regarding sponsorship of this year's workshop --> **Aung Tu**
2. Give an overview / update on the activities so far regarding GaN Standardization activities --> **Tim McDonald**
3. Give an update on activities related to PSMA roadmap --> **Tim McDonald**

Tim McDonald won't be able to attend tomorrow's call, but he sent an update - see below. We'll review this in the meeting and see who all would like to participate in the roadmap activity and also if there are any comments regarding the GaN standards.

Update from Tim:

A quick update of items that may of interest to the team for discussion:

1. Vittorio Crisafulli (On Semi) and I met and have started to craft a component section for the 2017 PSMA roadmap. This will include switches (LV, MV, HV FETs , IGBT's, SiC and GaN), drivers/ controllers, and also passives: capacitors and magnetics. We would like to lean heavily on contributions from other semiconductor team members for this activity. A template is being created and input will be sought. Please let me (Tim) know if you would like to participate or if you have recommendations for folks to cover the subject areas.
2. The GaN Standards working group is formed and working well. The PSMA board has approved sponsorship (see minutes excerpt below) and asks that involvement should be funneled through the Semiconductor Technical Committee. I am glad to provide that liason and network for involvement going forward. See attached an update of the Groups' work provided to JEDEC this week. Please direct any questions my way!

Regards,

-Ritu.